



Mechanical characterization of REBCO CC layer materials at the microscale

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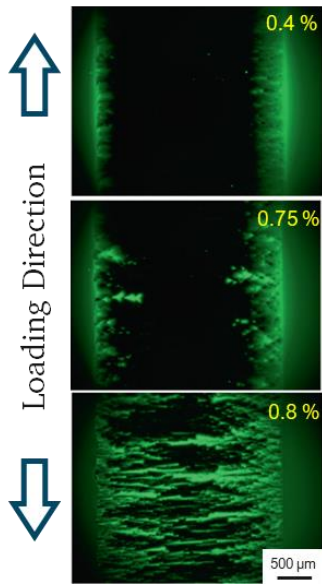
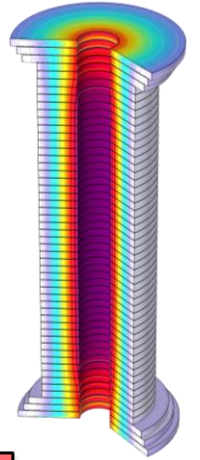
- Background
 1. Nanoindentation
 2. Micropillar compression
 3. Micropillar splitting
- Conclusions & Next steps
- Discussion

Why material properties ?

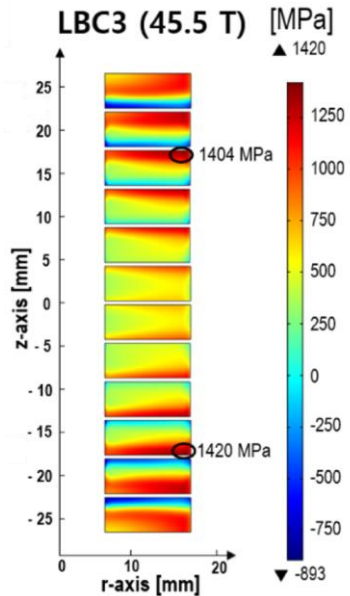
- High field → **high stresses**
- Plastic deformation
- Delamination

$$p_m = \frac{B^2}{2\mu_0} \quad p_m(50 \text{ T}) \sim 1 \text{ GPa}$$

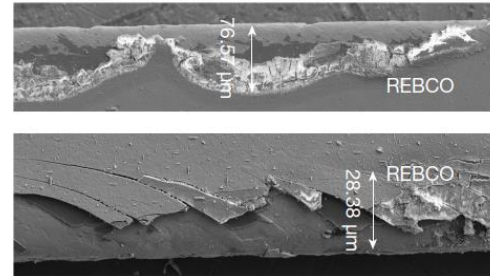
For the 40 T FC Solenoid:
extensive material characterization & modeling



Y.H. Zhou et al – Nature Communications (2021) 12:3110

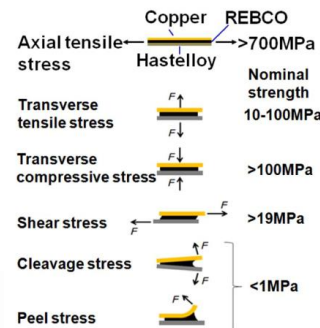


Xinbo Hu et al 2020 Supercond. Sci. Technol. 33 095012



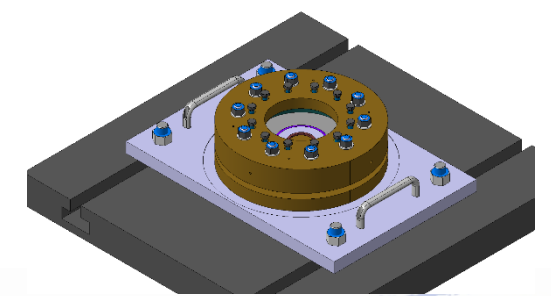
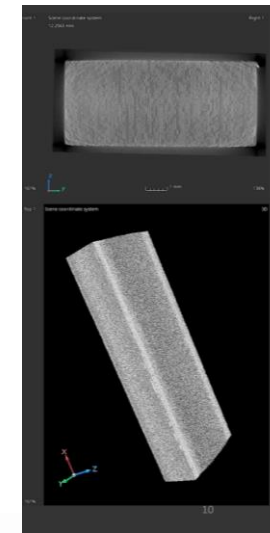
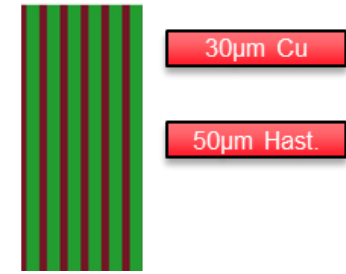
Xinbo Hu et al 2020 Supercond. Sci. Technol. 33 095012

REBCO conductor



H. Maeda et al, IEEE TAS, VOL. 24, NO. 3, 2014

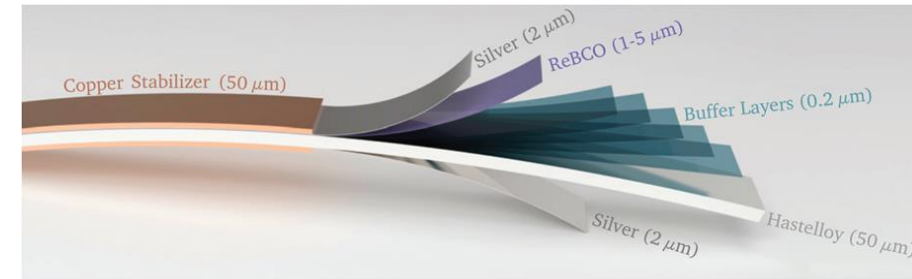
Coil



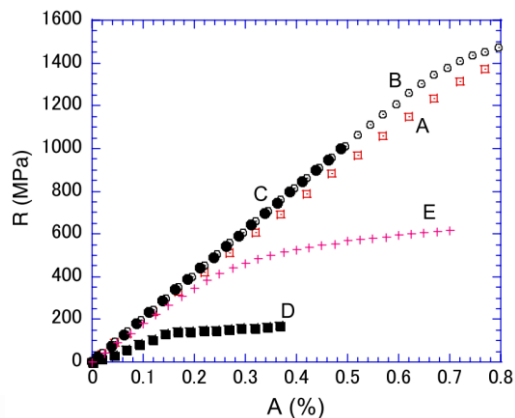
C. Accettura - Magnets R&D for the Muon Collider Study - <https://indico.cern.ch/event/1476966/>

Characterization: at which scale ?

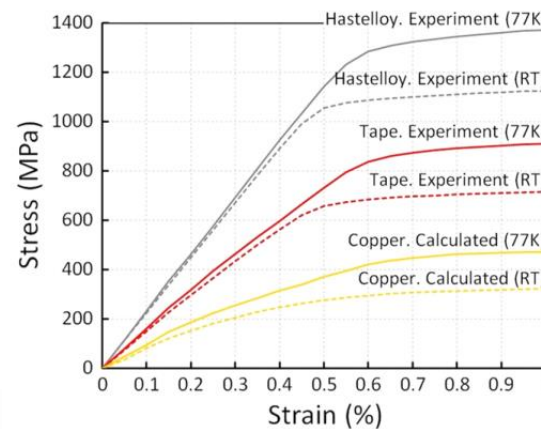
- REBCO CC are made of several thin layers (**0.1 – 100 μm**) of materials which behave mechanically very differently.
- The **limiting factors** for our applications (critical current degradation, delamination, etc.) occur at the **micro** scale.
- For a deeper understanding of the degradation mechanisms, we have to rely on properties measured at a coherent scale.



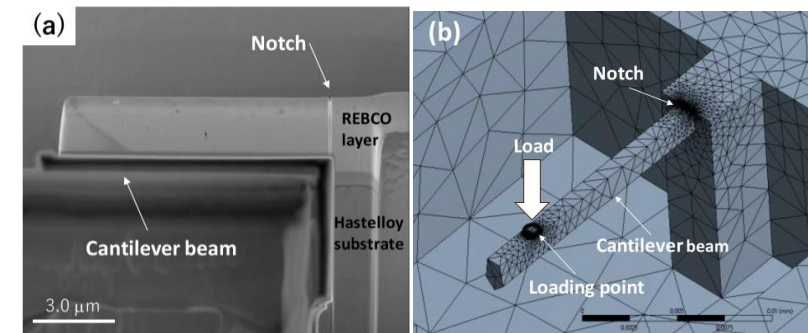
J. Van Nugteren, 2016



K. Osamura et Al., Supercond. Sci. Technol. 22 (2009)



Ilin et Al., Supercond. Sci. Technol. 28 (2015)

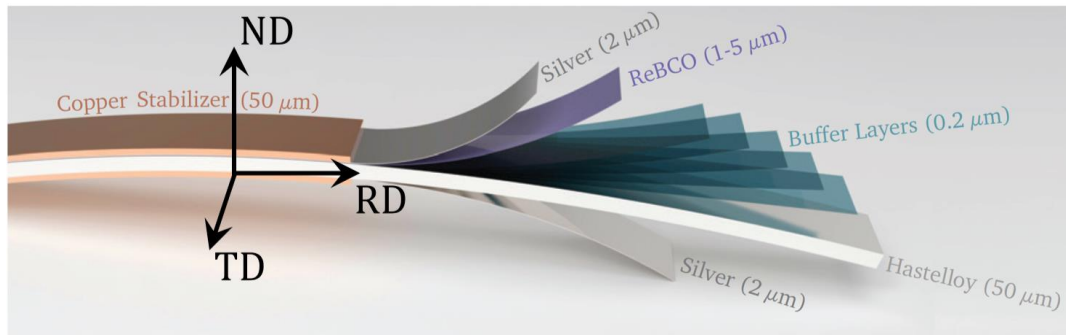


S. Muto et al., IEEE TAS 30, 4, 2020

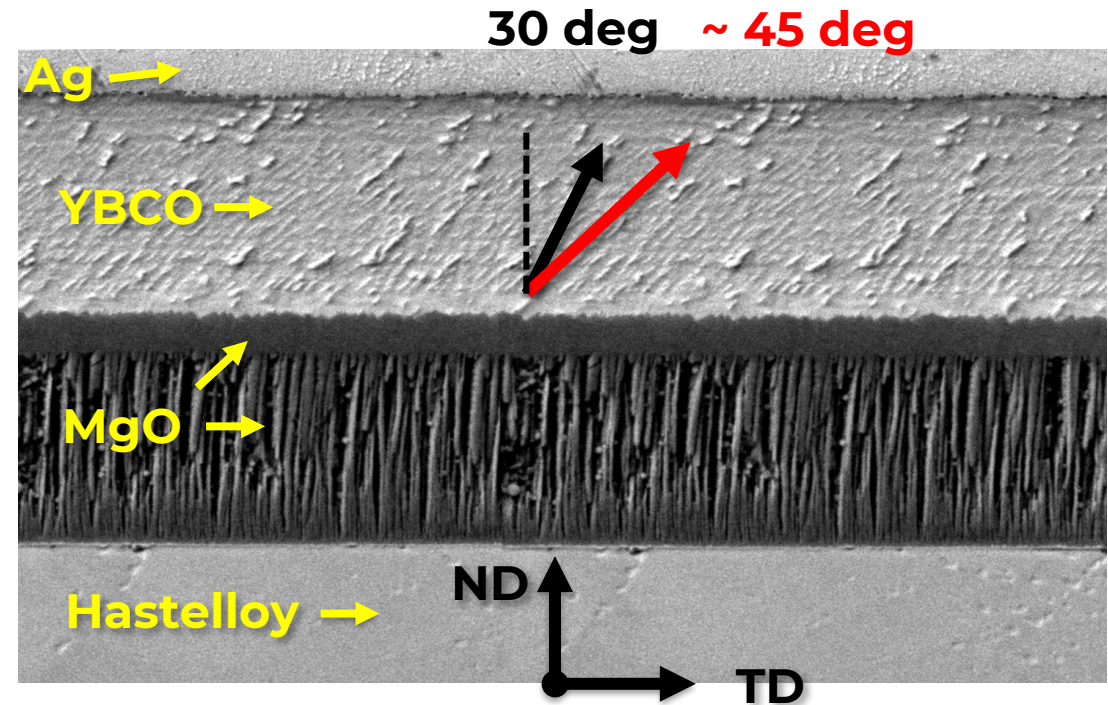
- Background
 - 1. Nanoindentation → Elastic-plastic behavior
 - 2. Micropillar compression → Plastic flow
 - 3. Micropillar splitting → Fracture toughness
- Conclusions & Next steps
- Discussion

Materials: YBCO tape from THEVA®

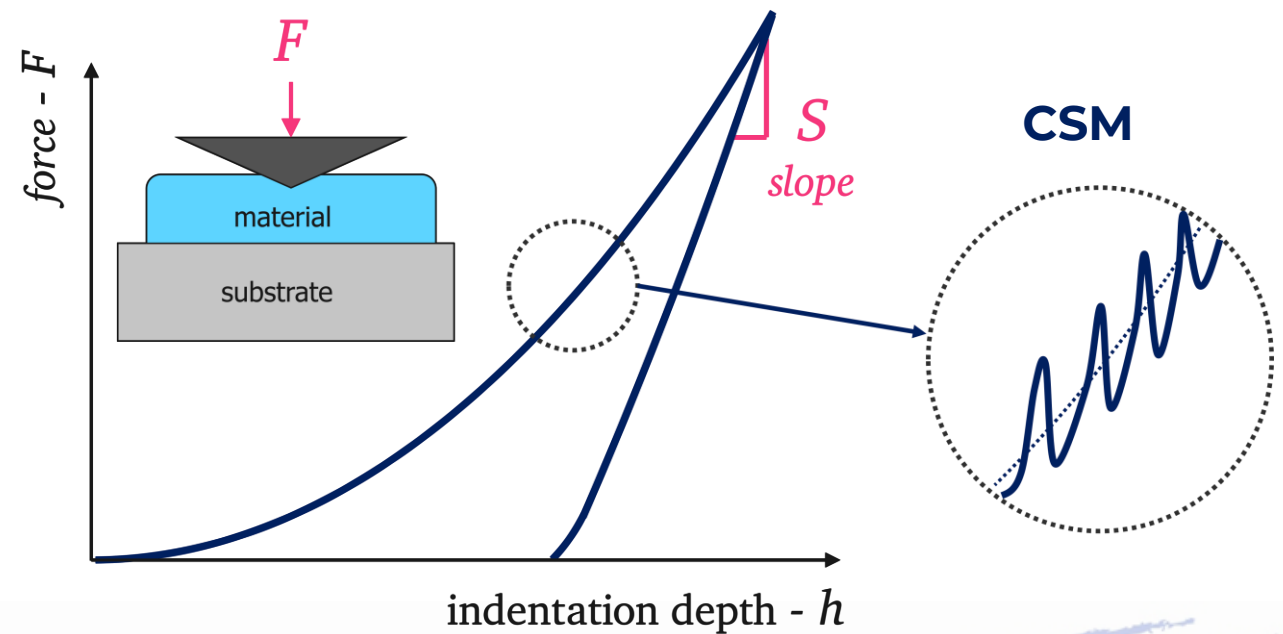
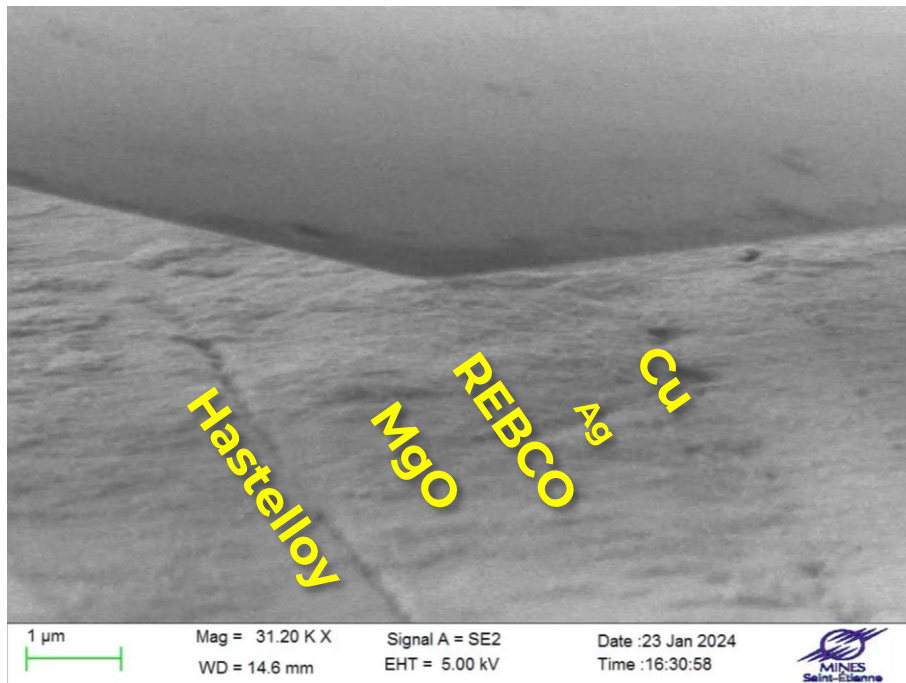
- THEVA® TPL4000-series: Inclined Substrate Deposition (30 deg)



J. Van Nugtereen, 2016

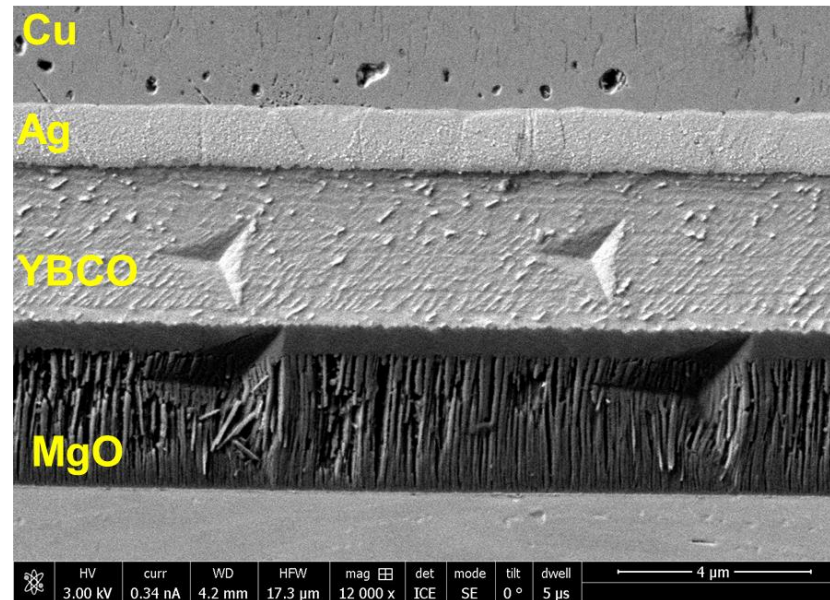
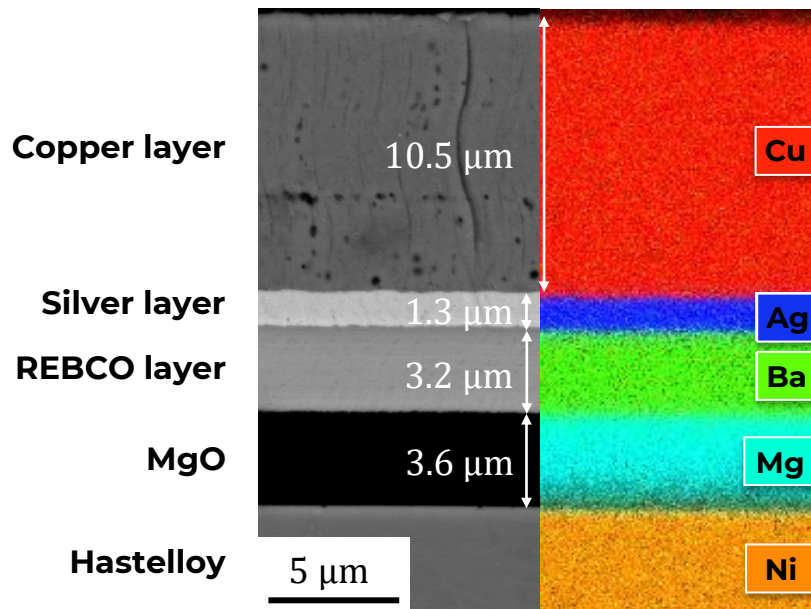


- Applying a controlled load F to a diamond tip and monitoring the penetration depth h inside the material.
- We measure the contact stiffness S and obtain the elastic modulus E and hardness H of the material.

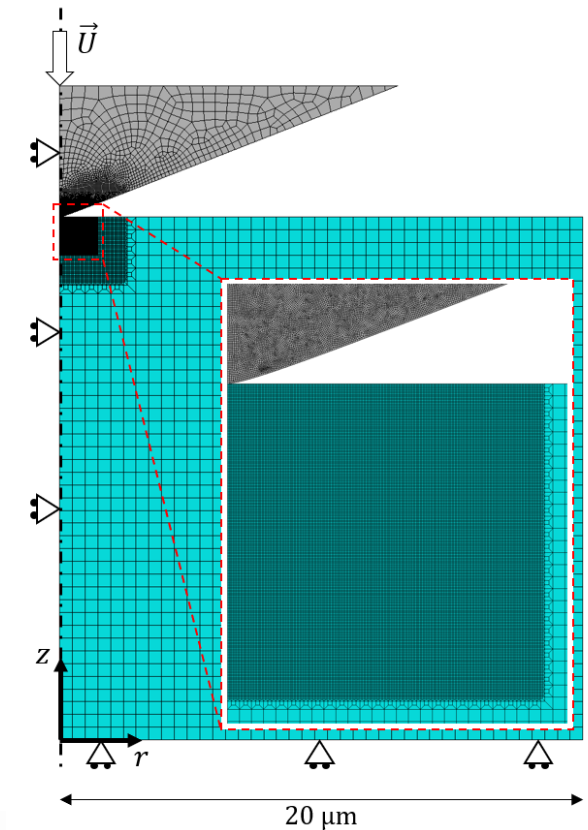


For REBCO & MgO:

- 5-10 indents optically targeted.
- Valid penetration depth < 150 nm.

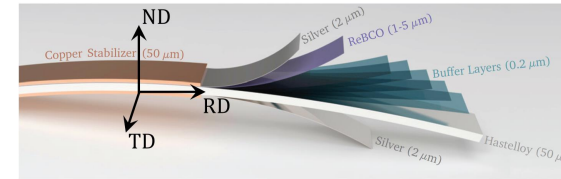


+ Coupled Mechanical
FE Model

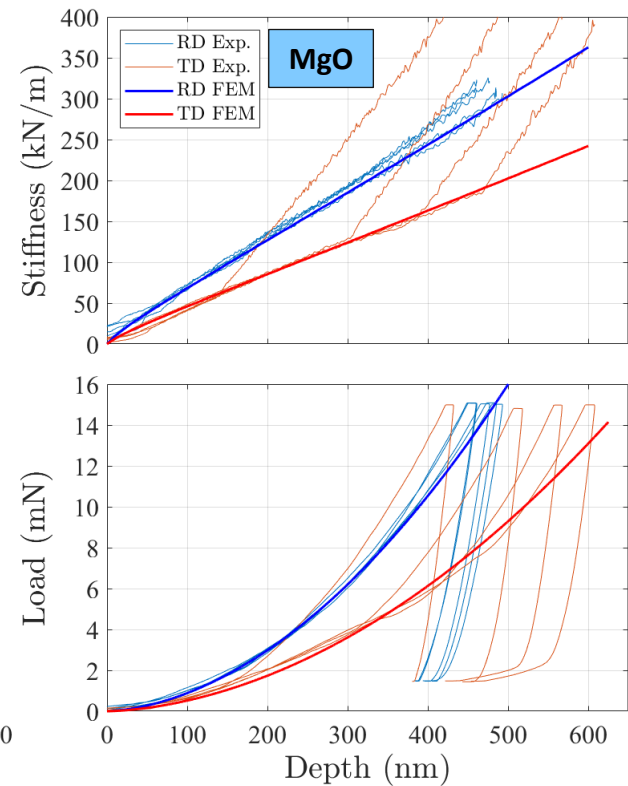
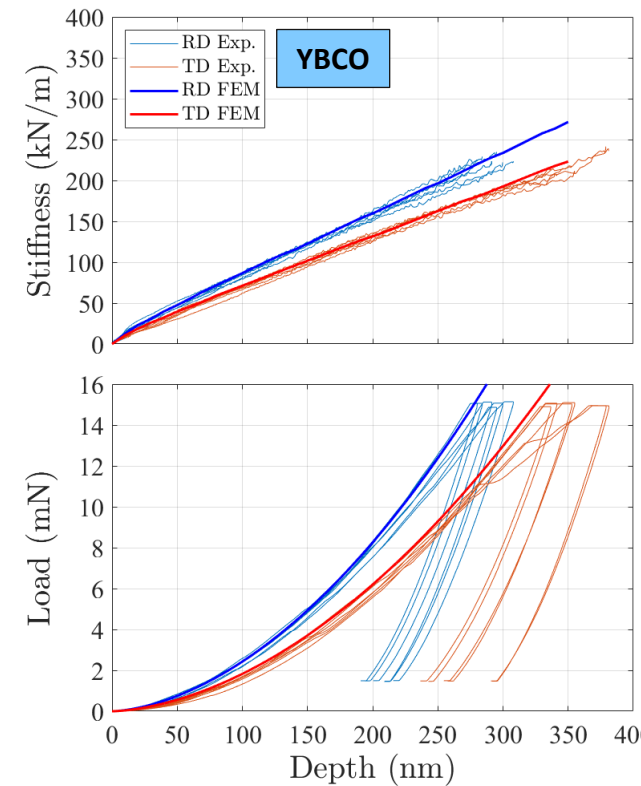
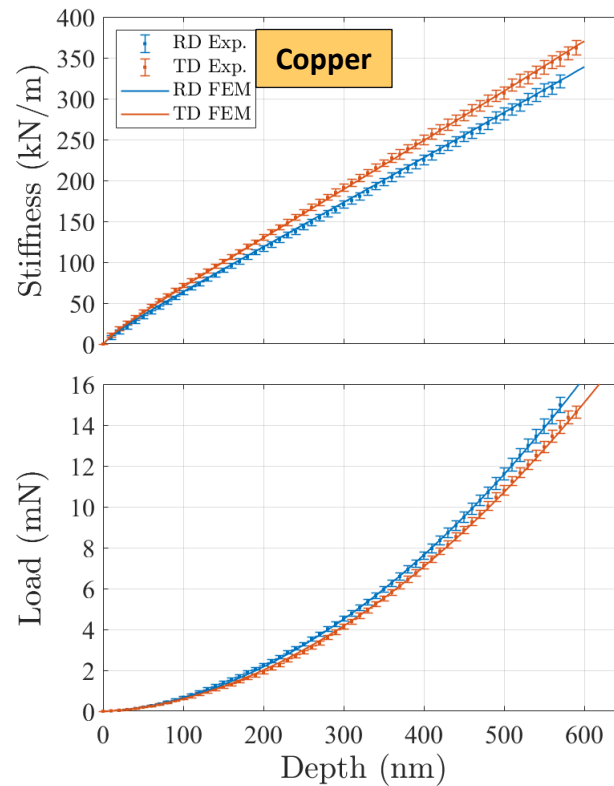
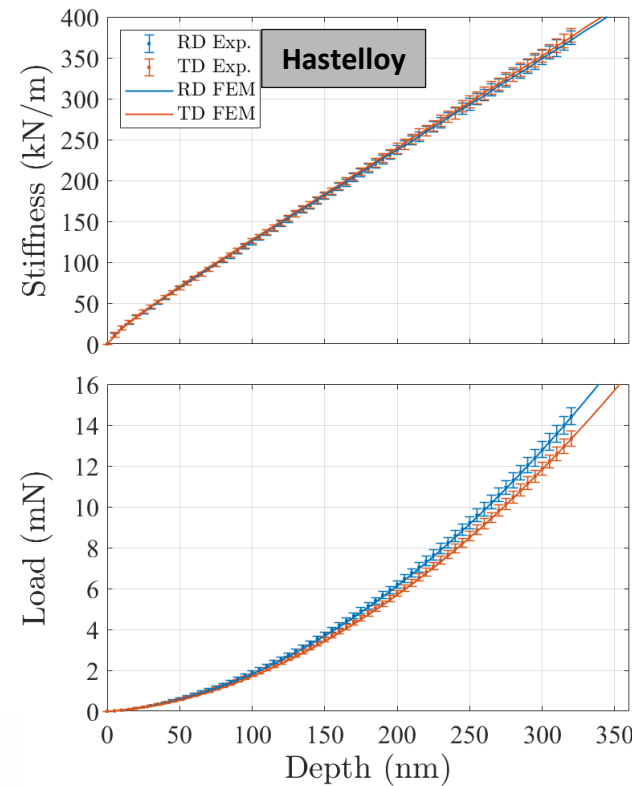
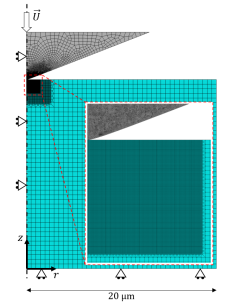


Nanoindentation: Results on THEVA[®] at Room Temperature

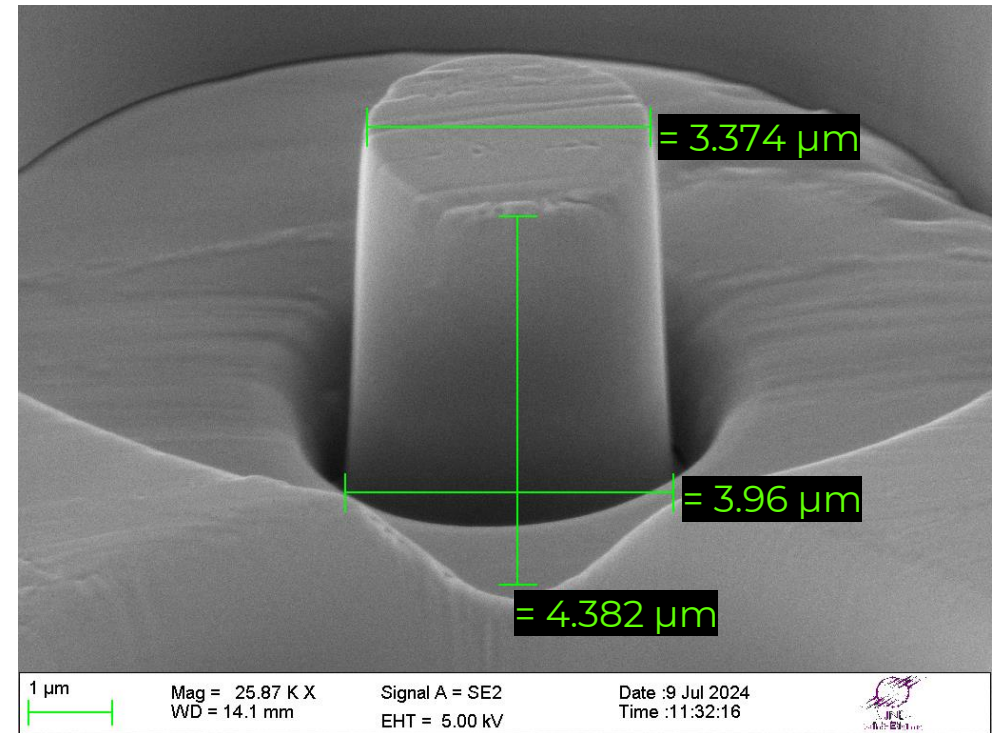
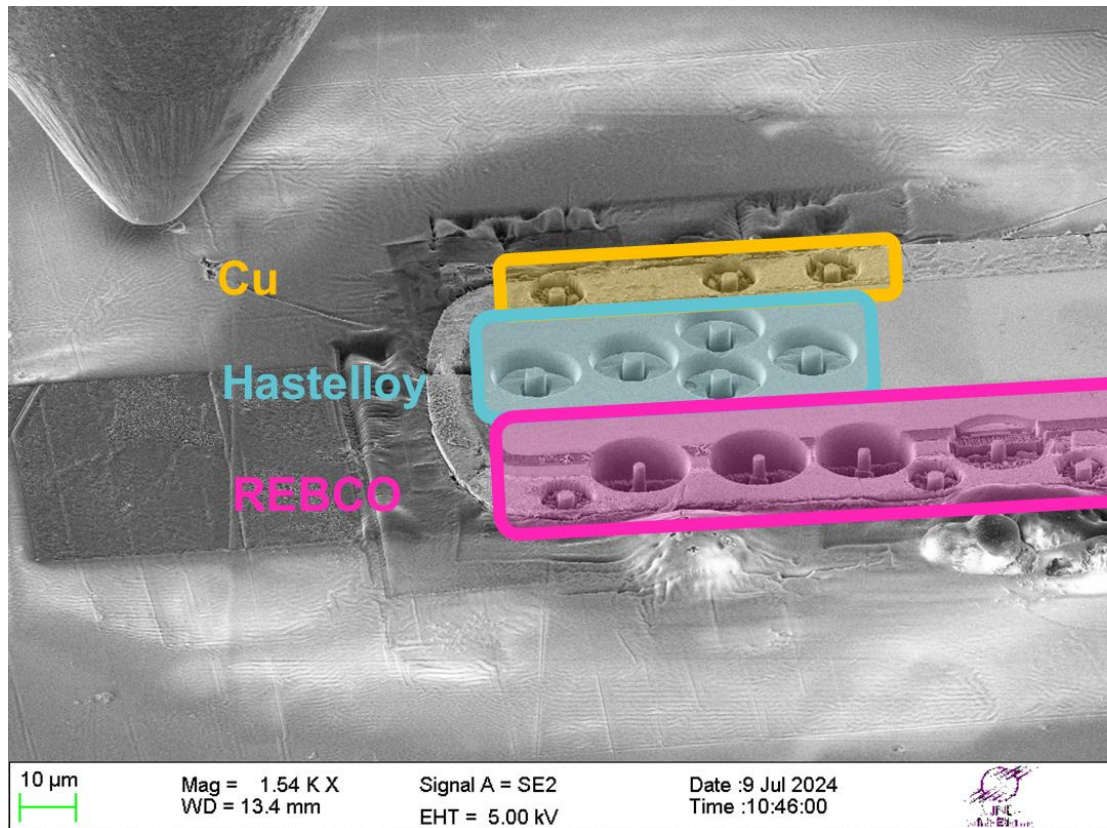
	Hastelloy	Copper	YBCO	MgO
	E (GPa)	E (GPa)	E (GPa)	E (GPa)
RD	197	84	155	95
TD	195	90	120	60



J. Van Nugteren, 2016

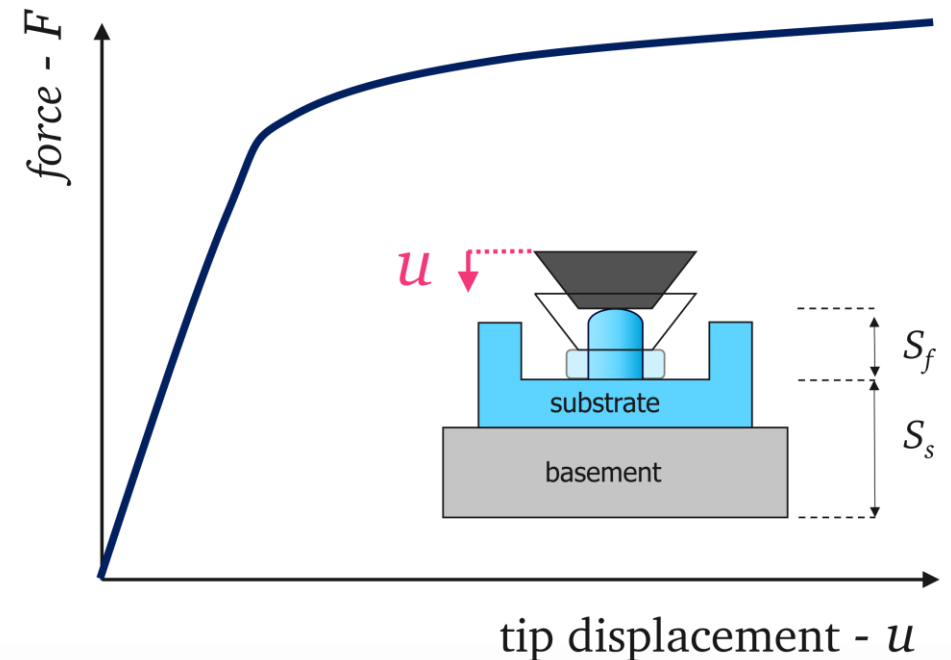
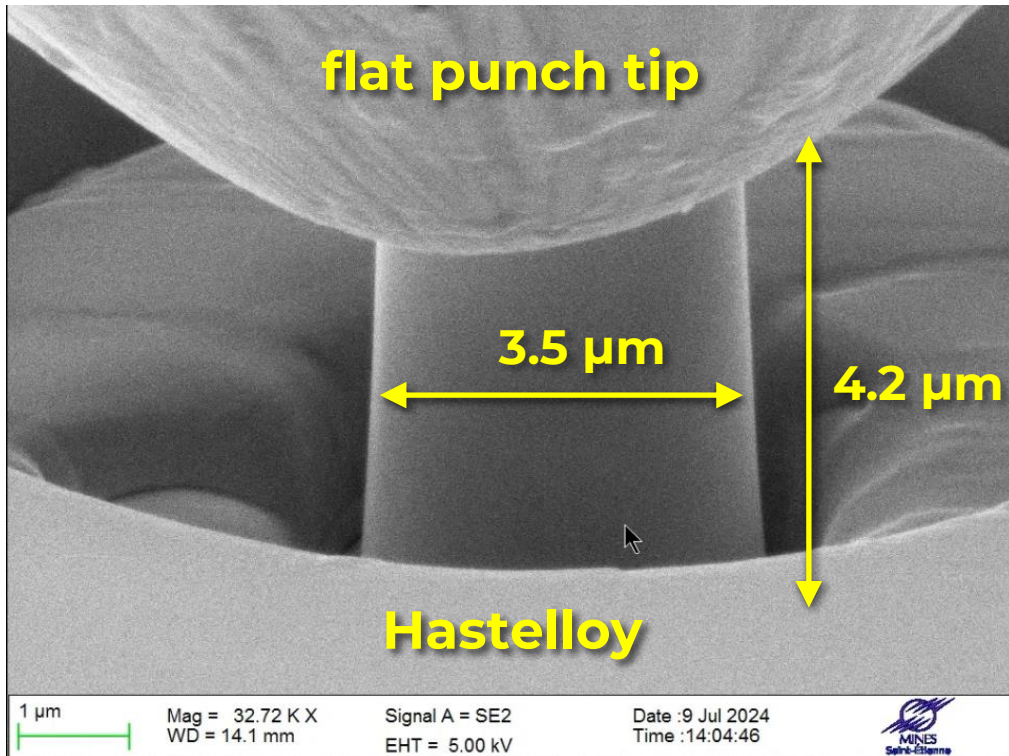


- FIB milling of micropillars

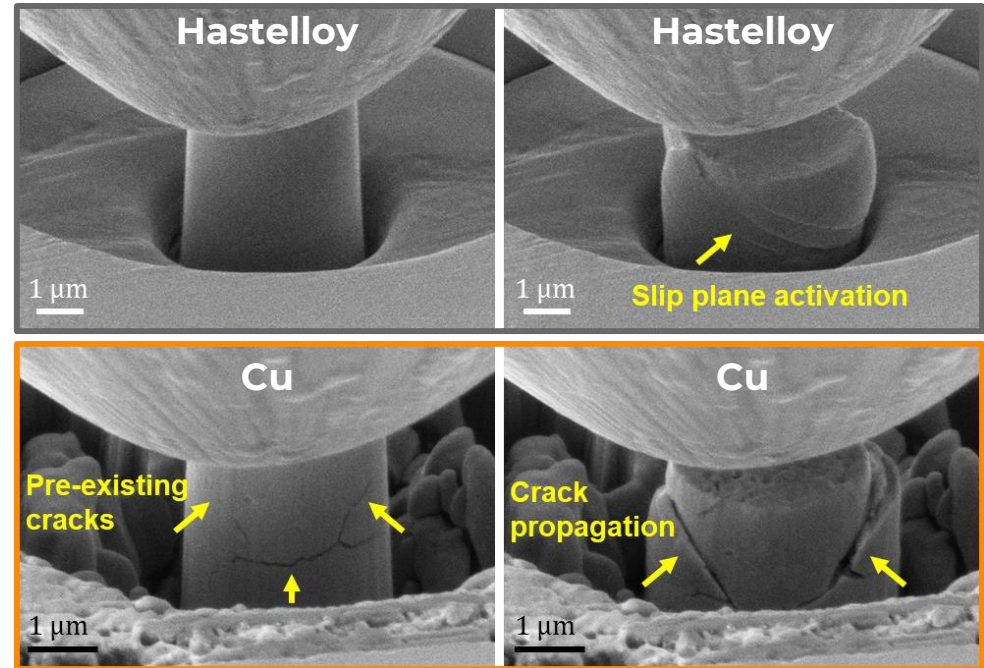
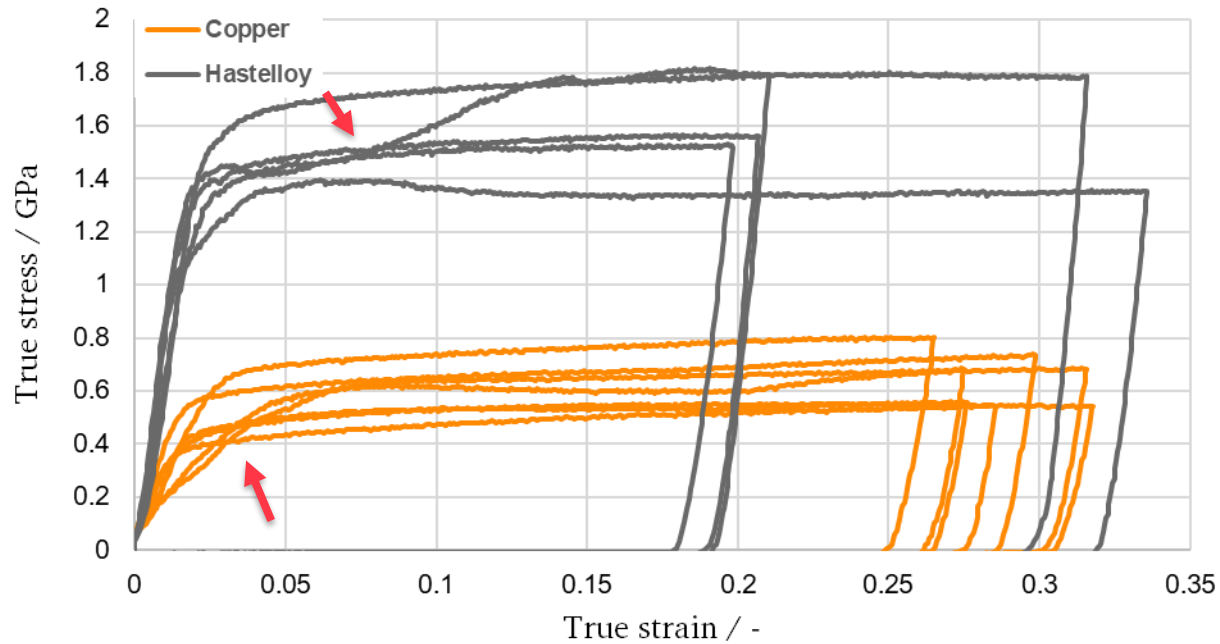


Micropillar compression: Introduction

- Applying a displacement u to a flat punch tip measuring the load response F .



Micropillar compression: Hastelloy & Copper



Hastelloy		Copper	
σ^y / GPa	* ϵ^y / %	σ^y / GPa	* ϵ^y / %
1.2 – 1.6	0.61 – 0.82	0.4 – 0.6	0.42 – 0.66

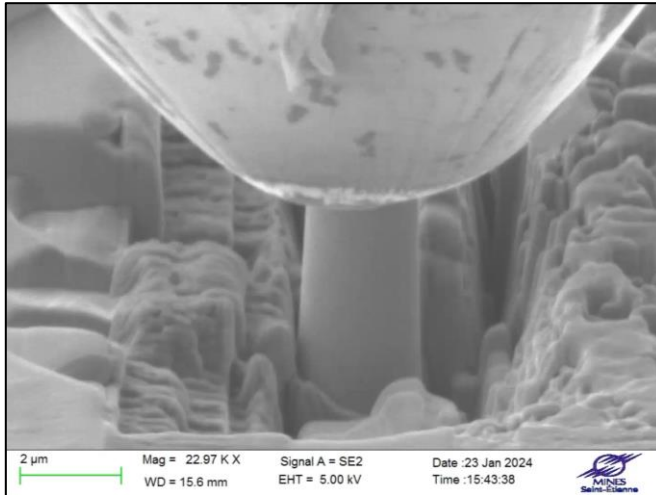
* using elastic moduli from nanoindentation measurements

Scattering between curves:

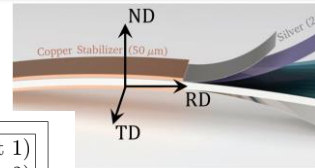
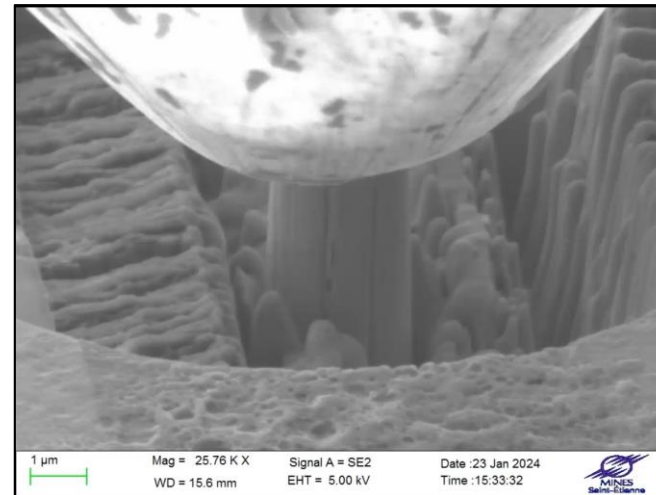
- Hastelloy: single/multiple slip plane activation
- Copper: pre-existing cracks

Micropillar compression: the anisotropy of RE(Y)-BCO

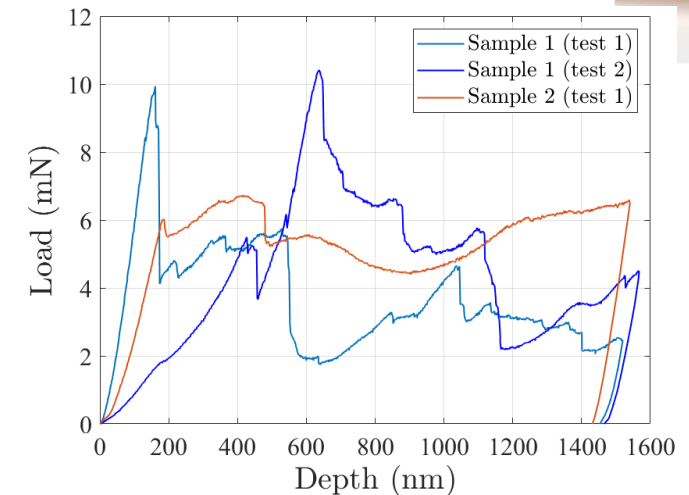
Sample 1 – TD



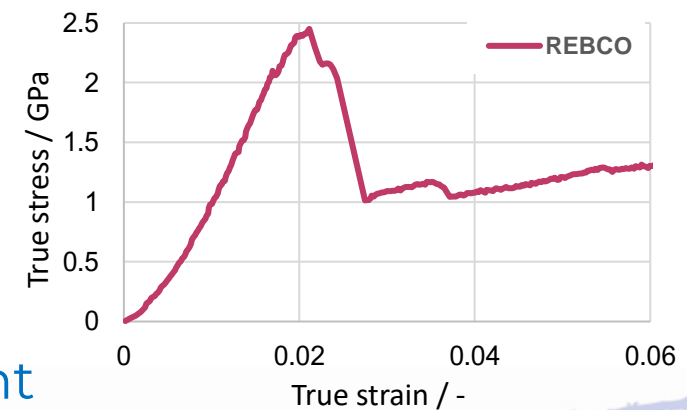
Sample 2 – RD



J. Van Nugteren,
2016

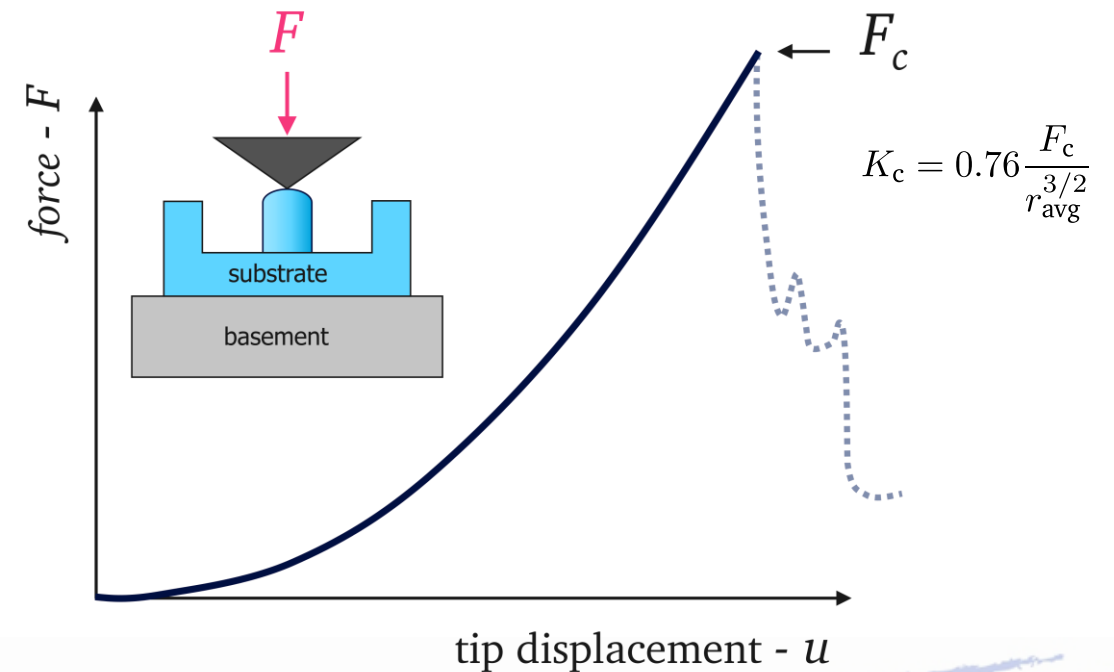
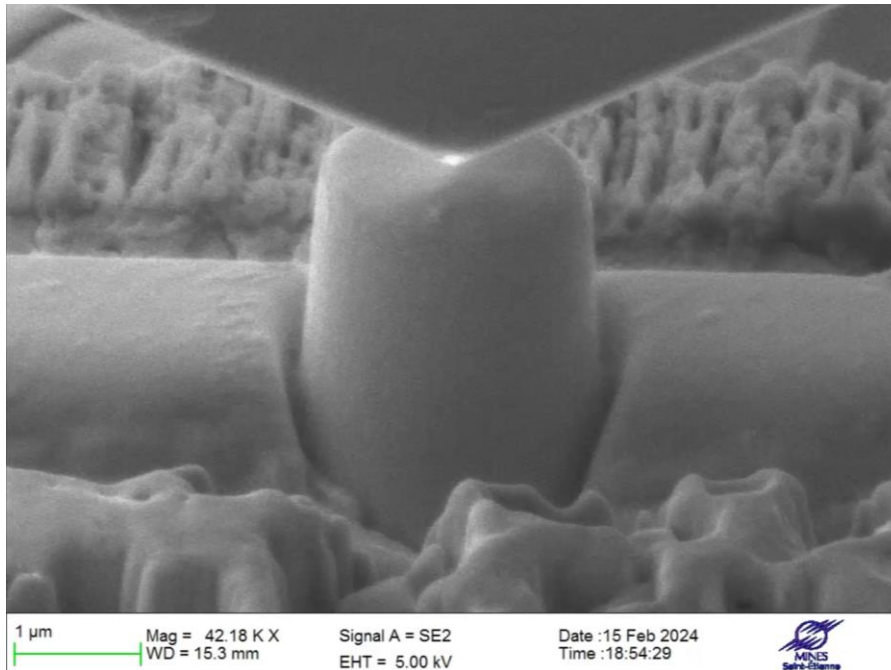


- Sample 1 exhibits brittle failure, as it occurs before any plastic deformation.
- Buckling / plastic failure depending on orientation.
- At the moment it is a non-conclusive measurements.
- Further investigation will be done on tapes of different manufacturers.

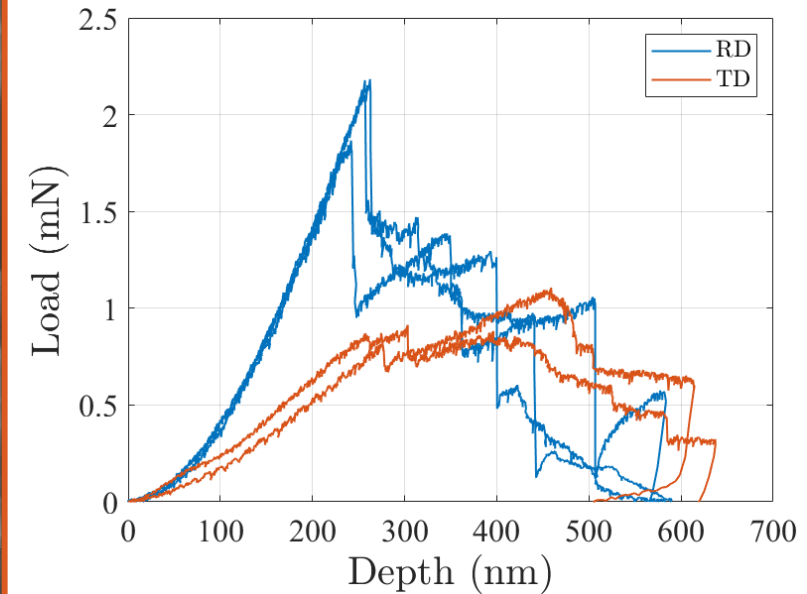
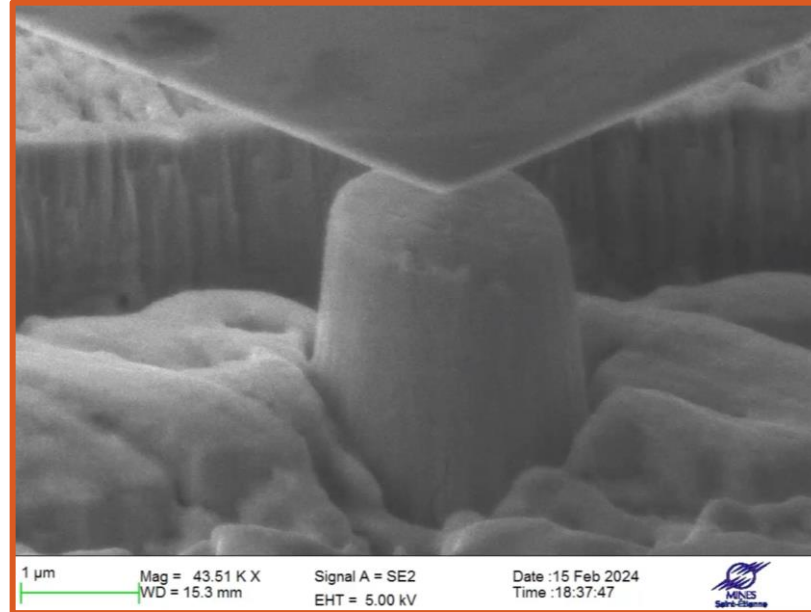
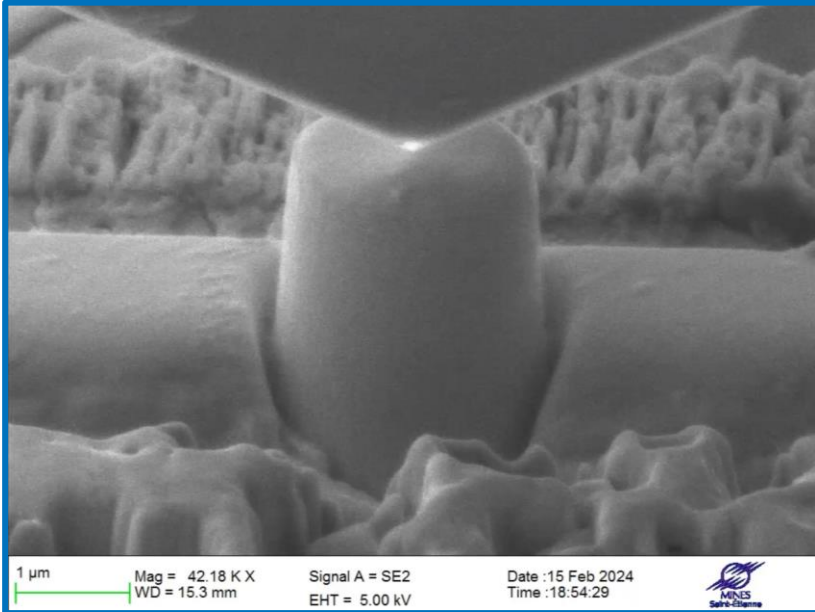


Micropillar splitting: Introduction

- Driving a sharp tip into a pillar until a fracture occurs. From the critical load F_c , we determine the fracture toughness K_c .



Micropillar splitting: RE(Y)-BCO



- Evident anisotropic behavior.
- Microstructural analyses needed for deeper understanding.
- Values of K_c are low with respect to traditional metals [ref.1] $K_c \sim 20 - 110 \text{ MPa}\cdot\sqrt{\text{m}}$, and ceramics, $K_c \sim 5 - 10 \text{ MPa}\cdot\sqrt{\text{m}}$.
- However, they agree with those found in literature [ref.2]

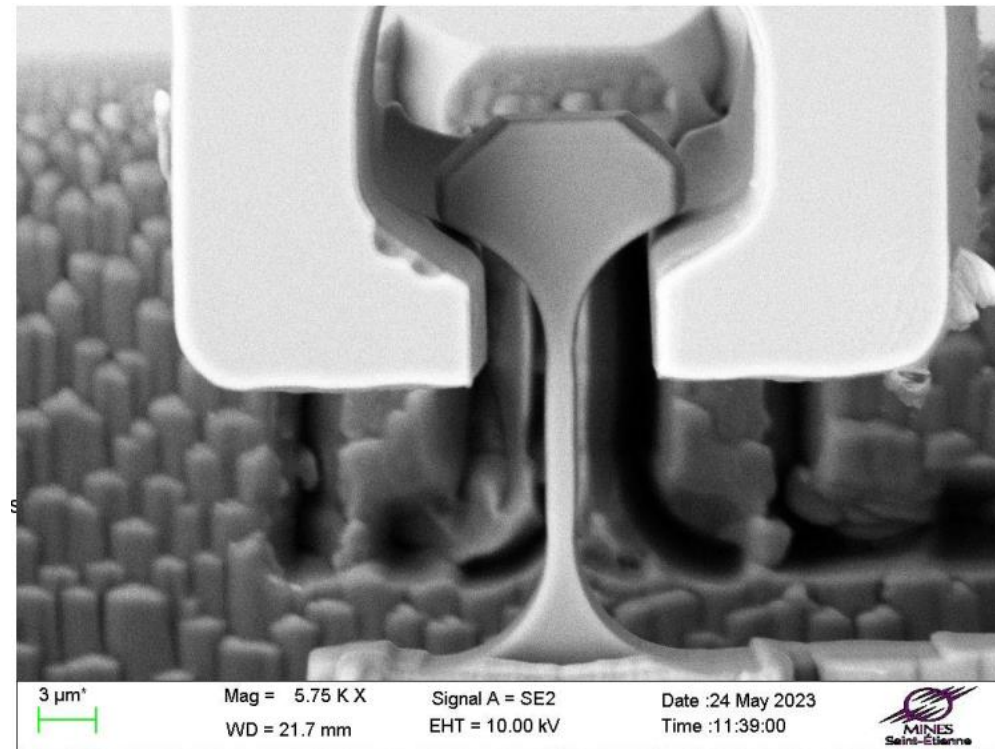
	REBCO		
	E (GPa)	σ_y (GPa)	K_c (MPa $\sqrt{\text{m}}$)
RD	155	4.00	1.34 ± 0.12
TD	120	2.80	0.56 ± 0.02

[ref.1]: MatWeb, online, accessible at <https://www.matweb.com/index.aspx>

[ref.2]: S. Muto et al., IEEE TAS 30, 4, 2020

- Nanoindentation measured reliably the **elastic properties** (of most) of the REBCO tape layer materials.
- Micropillar compression has highlighted the high **yield strength** of Hastelloy and Copper.
- Micropillar compression has shown the low **fracture toughness** of YBCO.

	REBCO		
	E (GPa)	σ_y (GPa)	K_c (MPa \sqrt{m})
RD	155	4.00	1.34 \pm 0.12
TD	120	2.80	0.56 \pm 0.02



Credit S Kalácska - Mines Saint-Etienne

- We are thinking of trying to characterize the mechanical delamination strength (MDS) at the microscale.

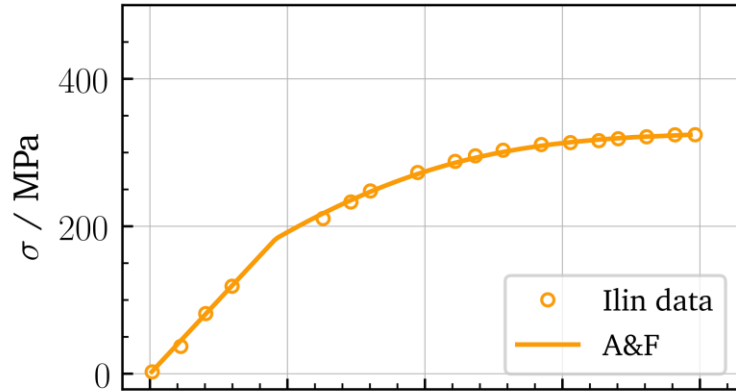


Thank you !

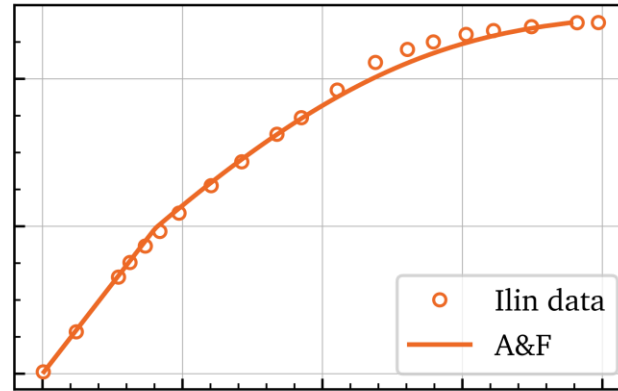
MMWG, 21.11.2024

Discussion: Properties from Ilin

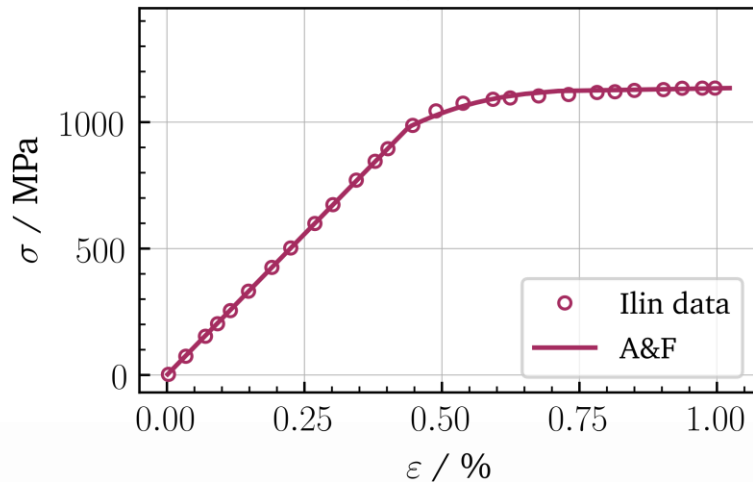
Copper at RT



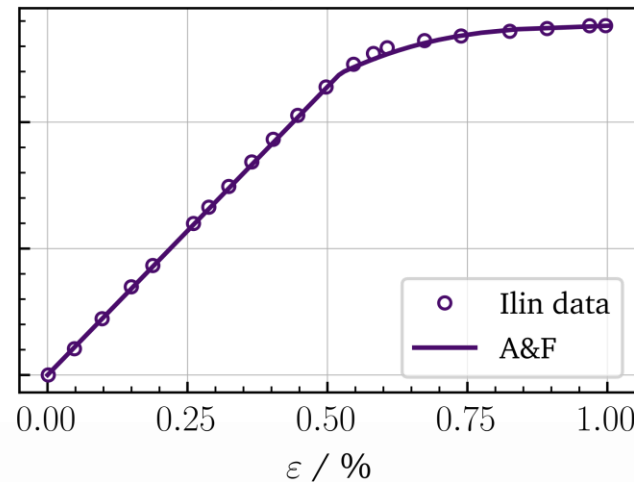
Copper at 77 K



Hastelloy C276 at RT



Hastelloy C276 at 77 K



$$f(\bar{\sigma}, R) = |\sigma| - \sigma^y - R$$

$$R = \frac{H}{\gamma} [1 - \exp(-\gamma p)]$$

$$p = \sqrt{\frac{2}{3}} \varepsilon^p : \varepsilon^p$$

Copper

	E_{Cu} / GPa	$\sigma^y_{Cu} / \text{MPa}$	H_{Cu} / GPa	γ_{Cu}
RT	80	183	91	629
77 K	98	197	191	648

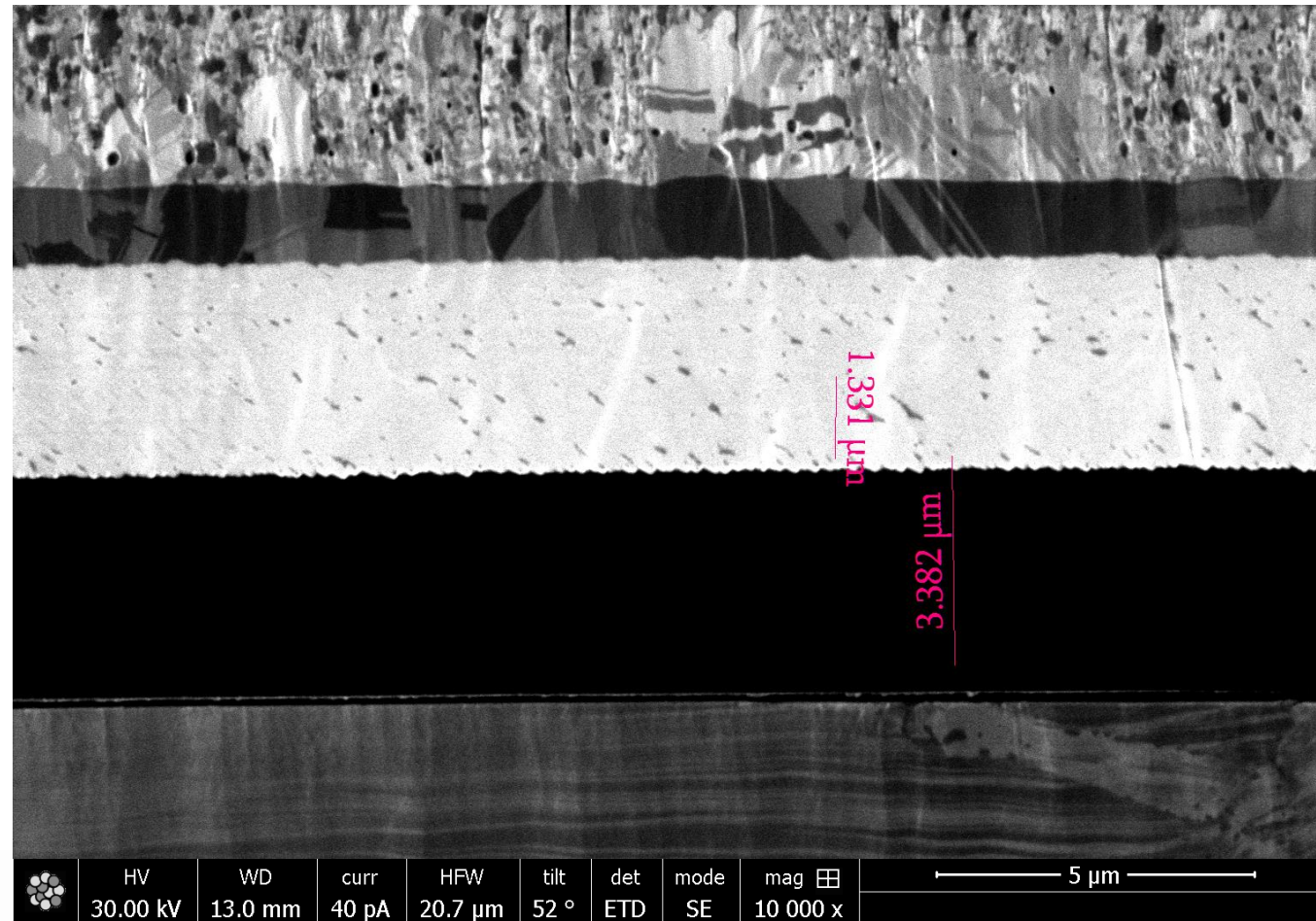
Hastelloy C276

	E_{C276} / GPa	$\sigma^y_{C276} / \text{MPa}$	H_{C276} / GPa	γ_{C276}
RT	223	981	191	1241
77 K	228	1194	190	995

tb, chaboche, mat_cu, 1
tbdata, 1, σ^y , H, γ

Grain sizes

- X-ray Photoelectric Spectroscopy images (XPS) showing the microstructures



The first slip occurs in crystals with crystallographic slip planes oriented at $\alpha = \pi/4$ to the direction of external stress.

Fig. 1.17. Deformation of a polycrystal.

